

DE LA RECHERCHE À L'INDUSTRIE



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STUDY OF 2D/3D BIO-INSPIRED DNA NANO-SCALE ASSEMBLY FOR ELECTRONICS INTERCONNECTIONS

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Objective - Demonstrator

Step 1 – DNA digestion / extraction / purification

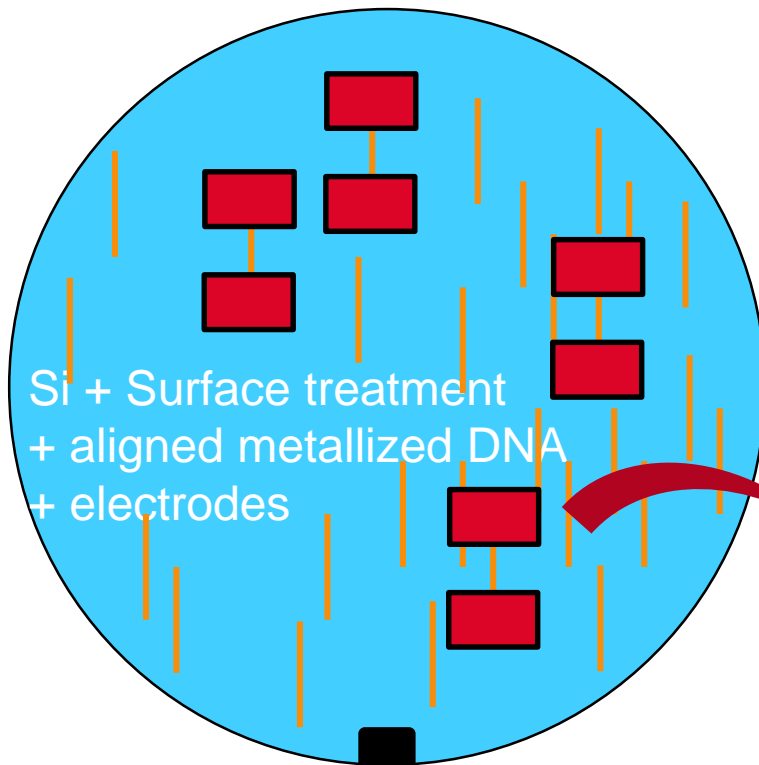
Step 2 - Surface treatments and DNA alignment

Step 3 – DNA metallization

Step 4 – DNA characterization

OBJECTIVE - DEMONSTRATOR

INTRODUCTION - CONTEXT

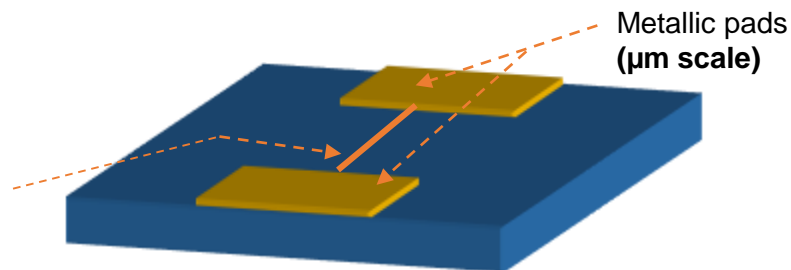


Control all nanowire
parameters (alignments,
length, diameter)

+

Statistical extraction of DNA
based nanowire electrical
properties

Interconnection :
Metallic DNA based
nanowire (**nm scale**)
D = 10-50 nm
L = 1-10 μm



DNA based nanowire between
two metallic electrodes

Aligned and metallized DNA
molecules on Si substrate
treated hydrophilic or
hydrophobic

STEP 1

DNA DIGESTION / EXTRACTION / PURIFICATION

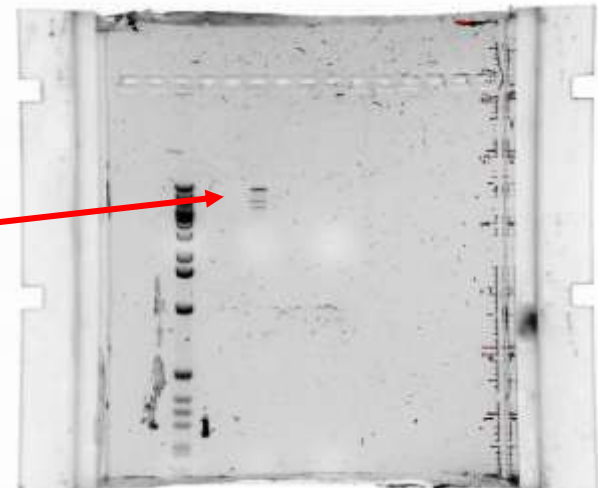
STEP 1 – DNA DIGESTION / EXTRACTION / PURIFICATION

- The objective is to access to 5 nanowire lengths: 1, 2, 5, 10 and 16 μm

Length / μm	Restriction site 1	Restriction site 2	Length achieved / μm
1	EcoRI	EcoRI	1.6 (4878 bp)
2	EcoRI	EcoRI	2.5 (7421)
5	BamHI	BamHI	5.7 (16841)
5	XhoI	End	5.1 (15005)
10	Start	XhoI	11.4 (33497)

2 contact lengths

- Digestion by enzymes done

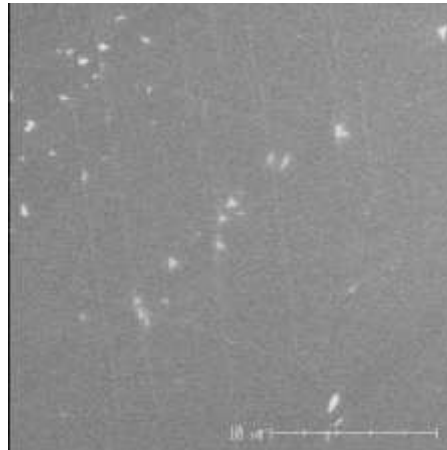
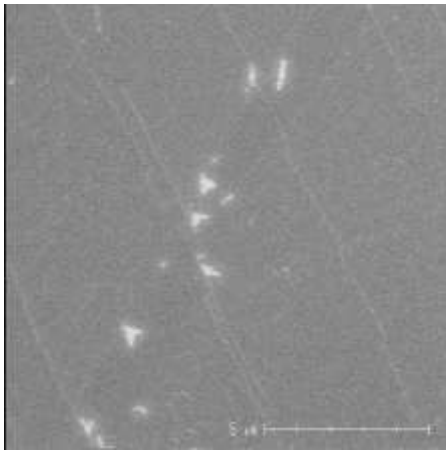


Good control of final DNA concentration

STEP 2
SURFACE TREATMENTS AND DNA
ALIGNMENT

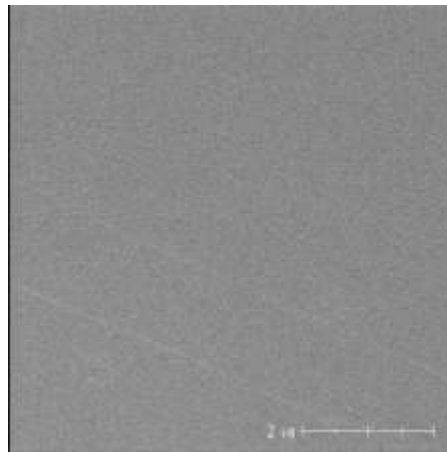
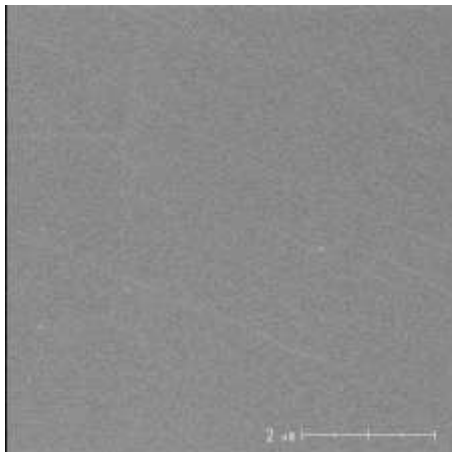
STEP 2 – SURFACE TREATMENTS AND DNA ALIGNMENT

■ DNA combing on HMDS treated Si surface by wetting and drop techniques



DNA combing by drop technique (pH 5.5, C=7.5 ng/μL)

- Correct alignment up to few dozen of microns
- Correct DNA concentration
- Wafer not perfectly clean at the water drop deposition
- DNA material deposited only at the drop location

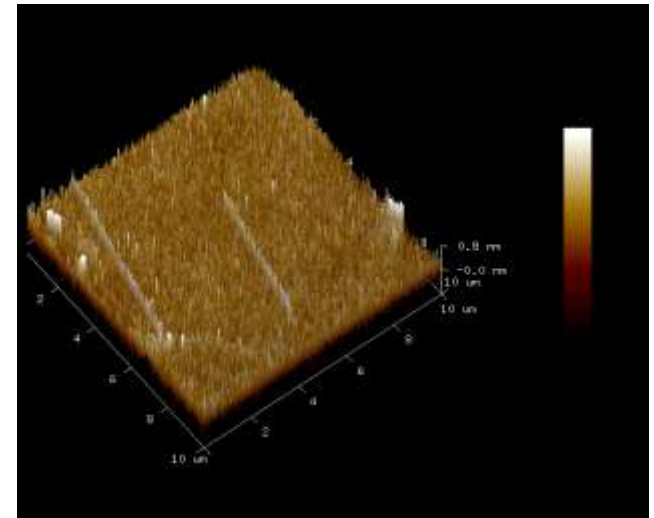
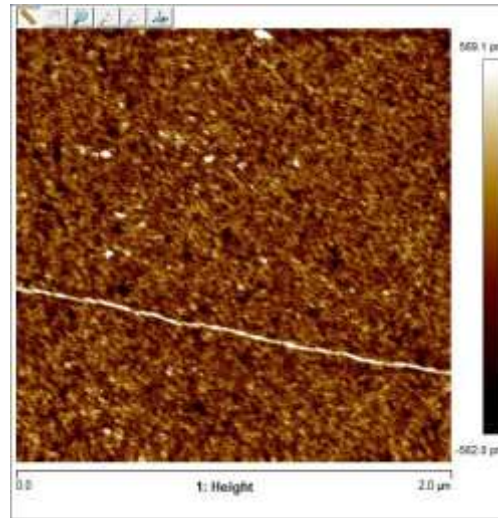
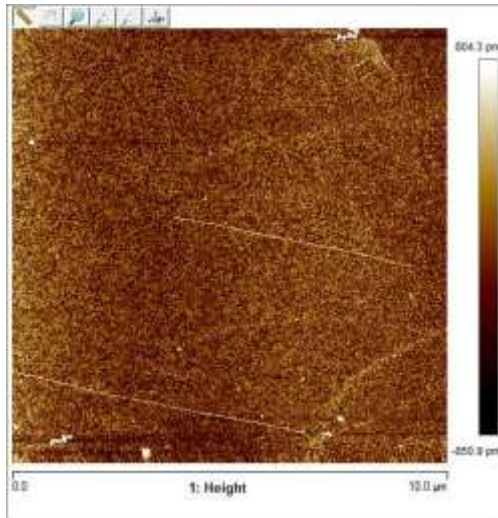


DNA combing by wetting technique (pH 5.5, C=7.5 ng/μL)

- Correct alignment up to few dozen of microns
- Correct DNA concentration
- Wafer perfectly clean
- DNA material deposited everywhere on the surface

STEP 2 – SURFACE TREATMENTS AND DNA ALIGNMENT

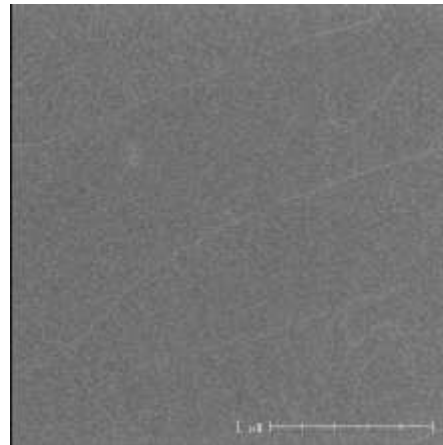
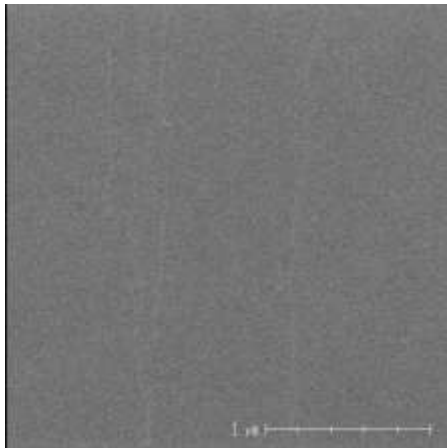
- DNA combing on HMDS treated Si surface by wetting and drop techniques



- 1-nm high average
- 15-nm diameter average -> error due the probe size (10 nm)
-> DNA diameter is about 4-6 nm

STEP 2 – SURFACE TREATMENTS AND DNA ALIGNMENT

- DNA combing on HMDS treated Si surface by wetting and drop techniques



DNA combing by wetting technique
(pH 5.7, C=15 ng/μL)
+ increase of NaCl concentration

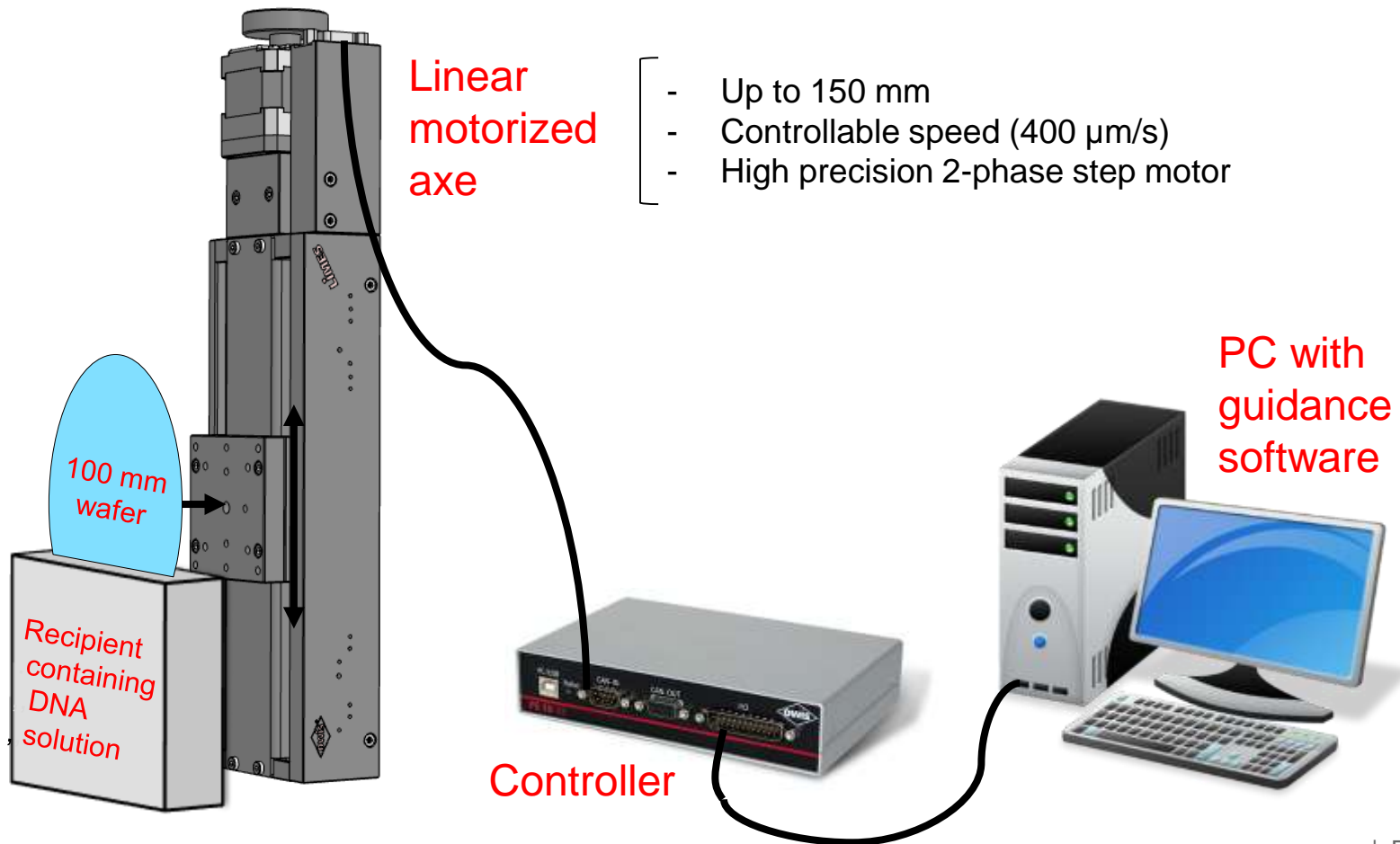
- Correct alignment
- Increase DNA concentration
- Wafer not perfectly clean at the water drop deposition
- DNA material deposited everywhere on the surface



Set up an equipment dedicated to DNA alignment

STEP 2 – SURFACE TREATMENTS AND DNA ALIGNMENT

- Set up an equipment dedicated to DNA alignment for better repeatability



STEP 3

DNA METALLIZATION

STEP 3 – DNA METALLIZATION

■ First try

- palladium nanowire:
 - * potassium tetrachloropalladate(II)
 - * borane-dimethylamine complex

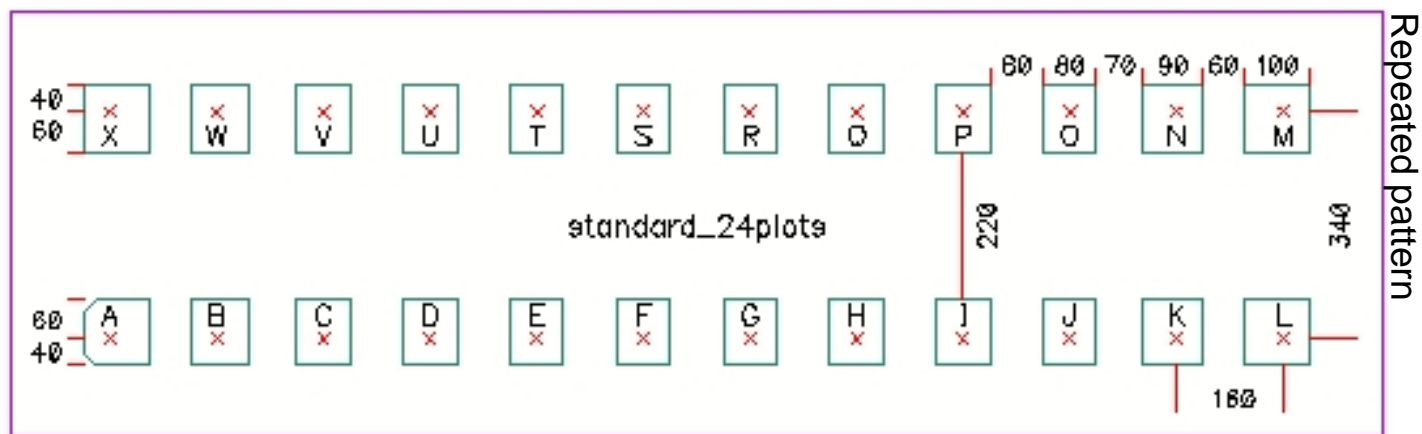
No success.. To be continued

STEP 4

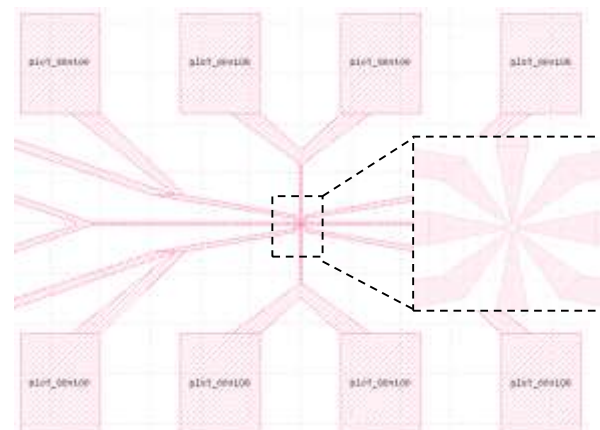
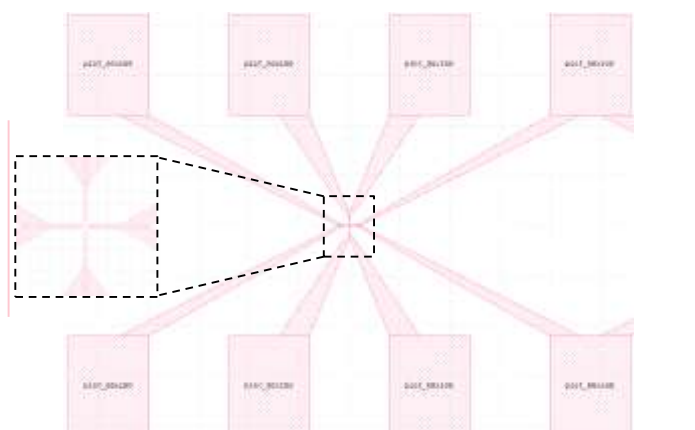
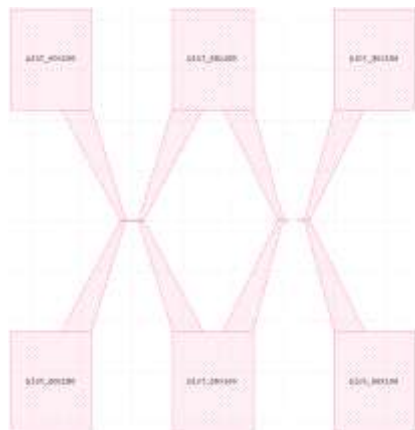
DNA CHARACTERIZATION

STEP 4 – DNA CHARACTERIZATION

- PTA equipment formation starting this week
- Mask design in progress: 2x12 fixed pads as template for automatic and statistic DC characterization

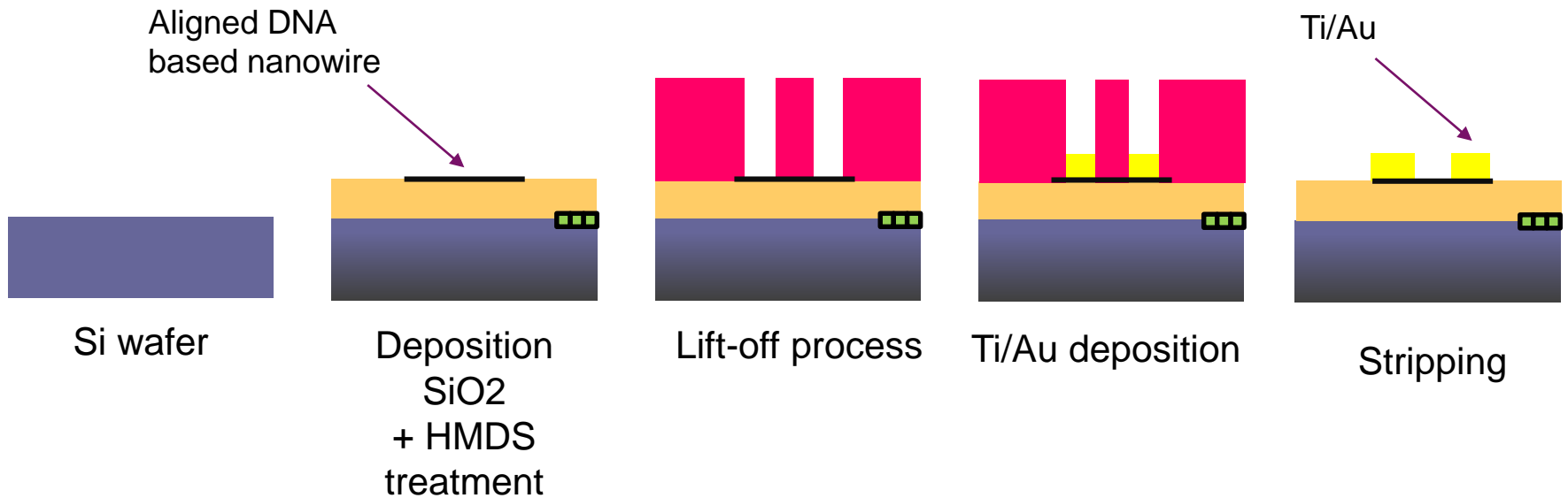


Smallest object
600 nm



STEP 4 – DNA CHARACTERIZATION

■ Process flow for gold electrodes fabrication:



Electrode thickness: 200 nm Ti + 200 nm Au ?